FILM PEELING METHOD AND FILM PEELING DEVICE

ABSTRACT OF THE DISCLOSURE

There is provided a film peeling device (100) for peeling a film (3) which has been stuck onto a film sticking face of a wafer (120), comprising: a wafer sucking means (31) for sucking the wafer so that the film sticking face of the wafer can become an upper face; a peeling tape feeding means (42) for feeding a peeling tape onto the film of the film sticking face; a pushing means (60) for pushing only one portion of the peeling tape against the film of the wafer at an edge portion of the wafer so that the adhesive strength between the peeling tape and the film can be enhanced in the one portion of the peeling tape; and a peeling means (44) for peeling the film from the film sticking face of the wafer by the peeling tape while the one portion of the peeling tape, the adhesive strength of which has been enhanced, is used as a peeling start portion. Therefore, it is possible to avoid damage to the wafer and an increase in size of the entire film peeling device.

(Fig. 2)